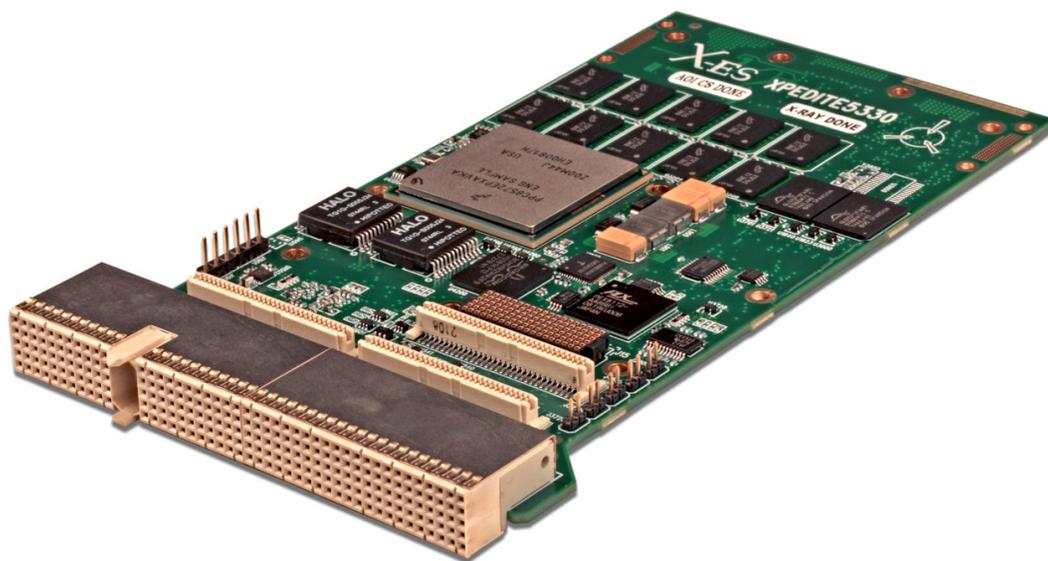


XPedite5330

End of Life

NXP PowerQUICC™ III MPC8572E Dual-Core Processor-Based Conduction- or Air-Cooled 3U cPCI SBC **Please contact X-ES Sales**

- ▶ NXP PowerQUICC™ III MPC8572E processor with dual PowerPC e500 cores at up to 1.5 GHz
- ▶ Conduction or air cooling
- ▶ Extended shock and vibration tolerance
- ▶ Up to 4 GB (2 GB each) DDR2-800 ECC SDRAM in two channels
- ▶ Configurable as system controller or peripheral
- ▶ Hosts an XMC or PrPMC
- ▶ PrPMC P14 I/O out J2
- ▶ Two 10/100/1000BASE-T Ethernet ports out J2
- ▶ Two RS-232/422/485 serial ports out J2
- ▶ Up to 256 MB of NOR flash (with redundancy)
- ▶ Up to 4 GB of NAND flash
- ▶ Front I/O available via plugover module
- ▶ Linux BSP
- ▶ Wind River VxWorks BSP
- ▶ QNX Neutrino BSP
- ▶ Green Hills INTEGRITY BSP



XPedite5330

The XPedite5330 is a conduction- or air-cooled 3U CompactPCI (cPCI) single board computer based on the NXP (formerly Freescale) PowerQUICC™ III MPC8572E processor. With dual PowerPC e500 cores running at up to 1.5 GHz, the MPC8572E delivers enhanced performance and efficiency for today's network information processing and other embedded computing applications.

Complementing processor performance, the XPedite5330 features two separate channels of up to 2 GB each of DDR2-667/800 ECC SDRAM, multiple PCI Express interfaces, XMC/PrPMC support, up to 256 MB of NOR flash (with redundancy), and up to 4 GB of NAND flash. Two Gigabit Ethernet ports, two RS-232/422/485 ports, and P14 I/O from the PrPMC are routed to J2 for additional system flexibility.

The XPedite5330 provides a high-performance, feature-rich solution for current and future generations of embedded applications. Operating system support packages for the XPedite5330 include Wind River VxWorks, Linux, QNX Neutrino, and Green Hills INTEGRITY.

X-ES

Extreme Engineering Solutions

...Always Fast

Extreme Engineering Solutions

9901 Silicon Prairie Parkway • Verona, WI 53593
 Phone: 608.833.1155 • Fax: 608.827.6171
 sales@xes-inc.com • <https://www.xes-inc.com>

Processor

- NXP (formerly Freescale) PowerQUICC™ III MPC8572E processor
- Dual PowerPC e500 cores at up to 1.5 GHz
- 1 MB of shared L2 cache

Memory

- Up to 4 GB (2 GB each) of DDR2-800 ECC SDRAM in two channels
- Up to 256 MB of NOR flash (with redundancy)
- Up to 4 GB of NAND flash

J1 cPCI Interface

- 32-bit PCI interface operating at 33 or 66 MHz
- System controller capable with onboard clocking and arbitration
- Peripheral slot capable

J2 cPCI Interface

- Two 10/100/1000BASE-T Ethernet ports
- Two RS-232/422/485 serial ports
- PrPMC P14 I/O
- Four GPIO signals

XMC/PrPMC Site

- 32-bit, 66 MHz PCI bus (PMC interface)
- x4 PCIe port (XMC interface)

Front Panel I/O

- Front panel dual RJ-45 Ethernet and micro-DB-9 RS-232 serial ports available via optional plugover module

Software

- Linux BSP
- Wind River VxWorks BSP
- QNX Neutrino BSP
- Green Hills INTEGRITY BSP

Physical Characteristics

- 3U CompactPCI conduction- or air-cooled form factor
- Dimensions: 100 mm x 160 mm

Environmental Requirements

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 3, 5
- Conformal coating available as an ordering option

Power Requirements

- Maximum power consumption: 27 W (with 1.5 GHz processor), 24 W (with 1.333 GHz processor)

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C (maximum)
Vibration	0.002 g ² /Hz (maximum), 5 to 2000 Hz	0.04 g ² /Hz (maximum), 5 to 2000 Hz	0.1 g ² /Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing

